+357 96 030922
info@marketpublishers.com

Global AI Chip Thermal Packaging Market 2026 by Company, Regions, Type and Application, Forecast to 2032

https://marketpublishers.com/r/GE59578D35CFEN.html
Date: September 2026
Pages: 96
Price: US$ 3,480.00 (Single User License)
ID: GE59578D35CFEN

Abstracts

According to our (Global Info Research) latest study, the global AI Chip Thermal Packaging market size was valued at US$ 2430 million in 2025 and is forecast to a readjusted size of US$ 7577 million by 2032 with a CAGR of 17.6% during review period.

AI Chip Thermal Packaging refers to advanced semiconductor packaging technologies designed to achieve electrical interconnection, mechanical protection, signal transmission and high-efficiency thermal management for high-performance AI processors, High Bandwidth Memory (HBM), GPUs and Chiplet-based heterogeneous integration architectures. The technology integrates advanced packaging structures, high thermal conductivity materials, thermal interface materials, heat dissipation solutions and liquid cooling compatible designs to address increasing power density and thermal challenges in AI computing systems. This market covers thermal management solutions applied during semiconductor packaging and integration processes, supporting AI servers, high-performance computing (HPC), data centers, autonomous driving platforms and next-generation intelligent computing systems.

Key Findings

AI chip thermal packaging is mainly driven by high-performance computing and AI server demand

HBM and advanced packaging technologies are becoming core directions for AI thermal management

+357 96 030922
info@marketpublishers.com

Asia Pacific represents the major manufacturing region for AI semiconductor packaging

High thermal conductivity materials and advanced cooling structures are gaining adoption

AI server applications are becoming the primary growth area for thermal packaging solutions

Market Trends

The AI Chip Thermal Packaging market is undergoing rapid transformation driven by increasing chip power consumption, higher transistor density and the expansion of heterogeneous integration architectures. Traditional packaging approaches are facing thermal limitations as AI accelerators, GPUs and HBM stacks continue to increase computing performance and heat flux density. Advanced packaging technologies such as 2.5D/3D integration, Chiplet architectures, hybrid bonding and high-density interconnect solutions are increasingly combined with enhanced thermal management structures. Future development is expected to focus on integrated thermal solutions combining advanced packaging materials, thermal interface technologies, embedded cooling structures and liquid cooling compatibility to support next-generation AI data centers and high-performance computing platforms.

Market Dynamics

Drivers

The primary growth drivers include rapid expansion of AI infrastructure, increasing deployment of AI servers, rising demand for GPUs and HBM memory, and continuous improvement of semiconductor performance requirements. As AI workloads become more computationally intensive, chip manufacturers and packaging companies are accelerating investment in advanced packaging technologies with improved thermal reliability. The transition toward higher power density processors is creating strong demand for thermal materials, advanced substrates and innovative cooling solutions.

+357 96 030922
info@marketpublishers.com

Restraints

The market faces challenges from high manufacturing complexity, expensive process equipment requirements and strict technology integration requirements. Advanced thermal packaging requires precise control of materials, interfaces and manufacturing processes, resulting in higher production costs and longer qualification cycles. Thermal reliability validation for advanced AI chips also increases development difficulty for suppliers.

Opportunities

Growth opportunities are emerging from AI data center expansion, next-generation GPU development, HBM technology evolution and increasing adoption of Chiplet-based architectures. Companies with capabilities in thermal materials, advanced packaging processes and system-level cooling integration are expected to benefit from increasing demand for high-performance computing solutions.

Challenges

Key industry challenges include managing extremely high heat flux density, improving thermal performance without increasing package size, reducing manufacturing costs and maintaining reliability under continuous AI workloads. The coordination between chip design, packaging technology and cooling infrastructure will become increasingly important for future AI computing systems.Industry Chain Analysis

The AI Chip Thermal Packaging industry chain consists of upstream materials, equipment and semiconductor manufacturing technologies, midstream advanced packaging and thermal solution providers, and downstream AI computing applications. The upstream segment includes thermal interface materials, high thermal conductivity materials, packaging substrates, semiconductor equipment and process technologies. The midstream segment focuses on advanced packaging integration, thermal structure design, HBM stacking, Chiplet packaging and cooling-compatible solutions. The downstream market is mainly driven by AI servers, data centers, autonomous driving systems and intelligent electronic devices. Value creation mainly comes from improving computing density, thermal reliability and energy efficiency of AI semiconductor systems.

+357 96 030922
info@marketpublishers.com

Segment Insights

AI Chip Thermal Packaging can be segmented by thermal technology roadmap, materials and application scenarios. Advanced packaging thermal management technologies represent the most strategically important segment due to increasing adoption of 2.5D/3D integration, HBM stacking and Chiplet architectures. Liquid cooling compatible chip packaging is becoming an emerging direction as AI processors require higher thermal removal capability. In materials, thermal interface materials and high thermal conductivity materials are gaining importance because they directly influence heat transfer efficiency and package reliability. The market structure is gradually shifting from conventional passive thermal solutions toward integrated thermal management systems combining packaging, materials and cooling technologies.

Downstream Market Opportunities

Data center AI servers represent the largest downstream opportunity for AI chip thermal packaging due to increasing deployment of AI accelerators, GPU clusters and HBM-based computing platforms. Autonomous driving AI chips and consumer AI devices also create additional demand for compact and efficient thermal solutions. Future opportunities will mainly come from hyperscale data centers, edge AI computing and high-performance intelligent systems requiring higher computing capability and improved thermal reliability.

Regional Insights

Asia Pacific is the core manufacturing region for AI chip thermal packaging, supported by a mature semiconductor ecosystem, advanced packaging capacity and strong supply chain integration. China, South Korea, Japan and Taiwan play important roles in semiconductor packaging, memory manufacturing, substrate materials and thermal technology development. North America maintains strong competitiveness in AI chip design, semiconductor innovation and advanced computing platforms, while Europe focuses on specialized semiconductor technologies and industrial applications. Regional competition is increasingly centered on advanced packaging capabilities, material innovation and AI semiconductor supply chain integration.

Competitive Landscape Analysis

+357 96 030922
info@marketpublishers.com

The competitive landscape of AI Chip Thermal Packaging is characterized by participation from semiconductor manufacturers, outsourced semiconductor assembly and test providers, memory companies and advanced packaging technology suppliers. Samsung Electronics and SK Hynix have strong capabilities in HBM-related technologies and advanced semiconductor integration. Amkor Technology, JCET Group, Tongfu Microelectronics and Huatian Technology represent important global packaging service providers with advanced packaging manufacturing capabilities. Intel continues to develop advanced packaging technologies through heterogeneous integration and high-performance computing solutions. Competition is increasingly focused on thermal technology innovation, advanced packaging capability, material integration and the ability to support next-generation AI computing architectures.

Report Scope

This report is a detailed and comprehensive analysis for global AI Chip Thermal Packaging market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global AI Chip Thermal Packaging market size and forecasts, in consumption value ($ Million), 2021-2032

Global AI Chip Thermal Packaging market size and forecasts by region and country, in consumption value ($ Million), 2021-2032

Global AI Chip Thermal Packaging market size and forecasts, by Type and by Application, in consumption value ($ Million), 2021-2032

Global AI Chip Thermal Packaging market shares of main players, in revenue ($ Million), 2021-2026

+357 96 030922
info@marketpublishers.com

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for AI Chip Thermal Packaging

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global AI Chip Thermal Packaging market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Samsung Electronics, Rapidus?, SK Hynix, Amkor Technology, JCET Group Co., Ltd., Tongfu Microelectronics Co., Ltd., Huatian Technology Co., Ltd., Shanghai Xianfeng Technology Co., Ltd., Intel, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

AI Chip Thermal Packaging market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segmentation

Market segment by Type

Traditional Passive Thermal Packaging

Advanced Packaging Thermal Management Technology

Liquid Cooling Compatible Chip Packaging

Others

+357 96 030922
info@marketpublishers.com

Market segment by Materials

Thermal Interface Materials (TIM)

High Thermal Conductivity Thermal Dissipation Materials

Packaging Substrate Materials

Market segment by Application

Data Center AI Servers

Autonomous Driving AI Chips

Consumer Electronics AI Chips

Others

Market segment by players, this report covers

Samsung Electronics

Rapidus?

SK Hynix

Amkor Technology

JCET Group Co., Ltd.

Tongfu Microelectronics Co., Ltd.

Huatian Technology Co., Ltd.

+357 96 030922
info@marketpublishers.com

Shanghai Xianfeng Technology Co., Ltd.

Intel

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

Chapter Outline

Chapter 1, to describe AI Chip Thermal Packaging product scope, market overview, market estimation caveats and base year.
Chapter 2, to profile the top players of AI Chip Thermal Packaging, with revenue, gross margin, and global market share of AI Chip Thermal Packaging from 2021 to 2026.
Chapter 3, the AI Chip Thermal Packaging competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.
Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2021 to 2032.
Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2021 to 2026.and AI Chip Thermal Packaging market forecast, by regions, by Type and by Application, with consumption value, from 2027 to 2032.
Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.
Chapter 12, the key raw materials and key suppliers, and industry chain of AI Chip Thermal Packaging.
Chapter 13, to describe AI Chip Thermal Packaging research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

1 MARKET OVERVIEW

1.1 Product Overview and Scope
1.2 Market Estimation Caveats and Base Year
1.3 Classification of AI Chip Thermal Packaging by Type
  1.3.1 Overview: Global AI Chip Thermal Packaging Market Size by Type: 2021 Versus 2025 Versus 2032
  1.3.2 Global AI Chip Thermal Packaging Consumption Value Market Share by Type in 2025
  1.3.3 Traditional Passive Thermal Packaging
  1.3.4 Advanced Packaging Thermal Management Technology
  1.3.5 Liquid Cooling Compatible Chip Packaging
  1.3.6 Others
1.4 Classification of AI Chip Thermal Packaging by Materials
  1.4.1 Overview: Global AI Chip Thermal Packaging Market Size by Materials: 2021 Versus 2025 Versus 2032
  1.4.2 Global AI Chip Thermal Packaging Consumption Value Market Share by Materials in 2025
  1.4.3 Thermal Interface Materials (TIM)
  1.4.4 High Thermal Conductivity Thermal Dissipation Materials
  1.4.5 Packaging Substrate Materials
1.5 Global AI Chip Thermal Packaging Market by Application
  1.5.1 Overview: Global AI Chip Thermal Packaging Market Size by Application: 2021 Versus 2025 Versus 2032
  1.5.2 Data Center AI Servers
  1.5.3 Autonomous Driving AI Chips
  1.5.4 Consumer Electronics AI Chips
  1.5.5 Others
1.6 Global AI Chip Thermal Packaging Market Size & Forecast
1.7 Global AI Chip Thermal Packaging Market Size and Forecast by Region
  1.7.1 Global AI Chip Thermal Packaging Market Size by Region: 2021 VS 2025 VS 2032
  1.7.2 Global AI Chip Thermal Packaging Market Size by Region, (2021-2032)
  1.7.3 North America AI Chip Thermal Packaging Market Size and Prospect (2021-2032)
  1.7.4 Europe AI Chip Thermal Packaging Market Size and Prospect (2021-2032)
  1.7.5 Asia-Pacific AI Chip Thermal Packaging Market Size and Prospect (2021-2032)

+357 96 030922
info@marketpublishers.com

1.7.6 South America AI Chip Thermal Packaging Market Size and Prospect (2021-2032)
1.7.7 Middle East & Africa AI Chip Thermal Packaging Market Size and Prospect (2021-2032)

2 COMPANY PROFILES

2.1 Samsung Electronics
2.1.1 Samsung Electronics Details
2.1.2 Samsung Electronics Major Business
2.1.3 Samsung Electronics AI Chip Thermal Packaging Product and Solutions
2.1.4 Samsung Electronics AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.1.5 Samsung Electronics Recent Developments and Future Plans
2.2 Rapidus?
2.2.1 Rapidus? Details
2.2.2 Rapidus? Major Business
2.2.3 Rapidus? AI Chip Thermal Packaging Product and Solutions
2.2.4 Rapidus? AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.2.5 Rapidus? Recent Developments and Future Plans
2.3 SK Hynix
2.3.1 SK Hynix Details
2.3.2 SK Hynix Major Business
2.3.3 SK Hynix AI Chip Thermal Packaging Product and Solutions
2.3.4 SK Hynix AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.3.5 SK Hynix Recent Developments and Future Plans
2.4 Amkor Technology
2.4.1 Amkor Technology Details
2.4.2 Amkor Technology Major Business
2.4.3 Amkor Technology AI Chip Thermal Packaging Product and Solutions
2.4.4 Amkor Technology AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.4.5 Amkor Technology Recent Developments and Future Plans
2.5 JCET Group Co., Ltd.
2.5.1 JCET Group Co., Ltd. Details
2.5.2 JCET Group Co., Ltd. Major Business
2.5.3 JCET Group Co., Ltd. AI Chip Thermal Packaging Product and Solutions

+357 96 030922
info@marketpublishers.com

2.5.4 JCET Group Co., Ltd. AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.5.5 JCET Group Co., Ltd. Recent Developments and Future Plans
2.6 Tongfu Microelectronics Co., Ltd.
2.6.1 Tongfu Microelectronics Co., Ltd. Details
2.6.2 Tongfu Microelectronics Co., Ltd. Major Business
2.6.3 Tongfu Microelectronics Co., Ltd. AI Chip Thermal Packaging Product and Solutions
2.6.4 Tongfu Microelectronics Co., Ltd. AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.6.5 Tongfu Microelectronics Co., Ltd. Recent Developments and Future Plans
2.7 Huatian Technology Co., Ltd.
2.7.1 Huatian Technology Co., Ltd. Details
2.7.2 Huatian Technology Co., Ltd. Major Business
2.7.3 Huatian Technology Co., Ltd. AI Chip Thermal Packaging Product and Solutions
2.7.4 Huatian Technology Co., Ltd. AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.7.5 Huatian Technology Co., Ltd. Recent Developments and Future Plans
2.8 Shanghai Xianfeng Technology Co., Ltd.
2.8.1 Shanghai Xianfeng Technology Co., Ltd. Details
2.8.2 Shanghai Xianfeng Technology Co., Ltd. Major Business
2.8.3 Shanghai Xianfeng Technology Co., Ltd. AI Chip Thermal Packaging Product and Solutions
2.8.4 Shanghai Xianfeng Technology Co., Ltd. AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.8.5 Shanghai Xianfeng Technology Co., Ltd. Recent Developments and Future Plans
2.9 Intel
2.9.1 Intel Details
2.9.2 Intel Major Business
2.9.3 Intel AI Chip Thermal Packaging Product and Solutions
2.9.4 Intel AI Chip Thermal Packaging Revenue, Gross Margin and Market Share (2021-2026)
2.9.5 Intel Recent Developments and Future Plans

3 MARKET COMPETITION, BY PLAYERS

3.1 Global AI Chip Thermal Packaging Revenue and Share by Players (2021-2026)
3.2 Market Share Analysis (2025)

+357 96 030922
info@marketpublishers.com

3.2.1 Market Share of AI Chip Thermal Packaging by Company Revenue
3.2.2 Top 3 AI Chip Thermal Packaging Players Market Share in 2025
3.2.3 Top 6 AI Chip Thermal Packaging Players Market Share in 2025
3.3 AI Chip Thermal Packaging Market: Overall Company Footprint Analysis
3.3.1 AI Chip Thermal Packaging Market: Region Footprint
3.3.2 AI Chip Thermal Packaging Market: Company Product Type Footprint
3.3.3 AI Chip Thermal Packaging Market: Company Product Application Footprint
3.4 New Market Entrants and Barriers to Market Entry
3.5 Mergers, Acquisition, Agreements, and Collaborations

4 MARKET SIZE SEGMENT BY TYPE

4.1 Global AI Chip Thermal Packaging Consumption Value and Market Share by Type (2021-2026)
4.2 Global AI Chip Thermal Packaging Market Forecast by Type (2027-2032)

5 MARKET SIZE SEGMENT BY APPLICATION

5.1 Global AI Chip Thermal Packaging Consumption Value Market Share by Application (2021-2026)
5.2 Global AI Chip Thermal Packaging Market Forecast by Application (2027-2032)

6 NORTH AMERICA

6.1 North America AI Chip Thermal Packaging Consumption Value by Type (2021-2032)
6.2 North America AI Chip Thermal Packaging Market Size by Application (2021-2032)
6.3 North America AI Chip Thermal Packaging Market Size by Country
6.3.1 North America AI Chip Thermal Packaging Consumption Value by Country (2021-2032)
6.3.2 United States AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
6.3.3 Canada AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
6.3.4 Mexico AI Chip Thermal Packaging Market Size and Forecast (2021-2032)

7 EUROPE

7.1 Europe AI Chip Thermal Packaging Consumption Value by Type (2021-2032)
7.2 Europe AI Chip Thermal Packaging Consumption Value by Application (2021-2032)
7.3 Europe AI Chip Thermal Packaging Market Size by Country

+357 96 030922
info@marketpublishers.com

7.3.1 Europe AI Chip Thermal Packaging Consumption Value by Country (2021-2032)
7.3.2 Germany AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
7.3.3 France AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
7.3.4 United Kingdom AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
7.3.5 Russia AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
7.3.6 Italy AI Chip Thermal Packaging Market Size and Forecast (2021-2032)

8 ASIA-PACIFIC

8.1 Asia-Pacific AI Chip Thermal Packaging Consumption Value by Type (2021-2032)
8.2 Asia-Pacific AI Chip Thermal Packaging Consumption Value by Application (2021-2032)
8.3 Asia-Pacific AI Chip Thermal Packaging Market Size by Region
8.3.1 Asia-Pacific AI Chip Thermal Packaging Consumption Value by Region (2021-2032)
8.3.2 China AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
8.3.3 Japan AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
8.3.4 South Korea AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
8.3.5 India AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
8.3.6 Southeast Asia AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
8.3.7 Australia AI Chip Thermal Packaging Market Size and Forecast (2021-2032)

9 SOUTH AMERICA

9.1 South America AI Chip Thermal Packaging Consumption Value by Type (2021-2032)
9.2 South America AI Chip Thermal Packaging Consumption Value by Application (2021-2032)
9.3 South America AI Chip Thermal Packaging Market Size by Country
9.3.1 South America AI Chip Thermal Packaging Consumption Value by Country (2021-2032)
9.3.2 Brazil AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
9.3.3 Argentina AI Chip Thermal Packaging Market Size and Forecast (2021-2032)

10 MIDDLE EAST & AFRICA

10.1 Middle East & Africa AI Chip Thermal Packaging Consumption Value by Type

+357 96 030922
info@marketpublishers.com

(2021-2032)
10.2 Middle East & Africa AI Chip Thermal Packaging Consumption Value by Application (2021-2032)
10.3 Middle East & Africa AI Chip Thermal Packaging Market Size by Country
  10.3.1 Middle East & Africa AI Chip Thermal Packaging Consumption Value by Country (2021-2032)
  10.3.2 Turkey AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
  10.3.3 Saudi Arabia AI Chip Thermal Packaging Market Size and Forecast (2021-2032)
  10.3.4 UAE AI Chip Thermal Packaging Market Size and Forecast (2021-2032)

11 MARKET DYNAMICS

11.1 AI Chip Thermal Packaging Market Drivers
11.2 AI Chip Thermal Packaging Market Restraints
11.3 AI Chip Thermal Packaging Trends Analysis
11.4 Porters Five Forces Analysis
  11.4.1 Threat of New Entrants
  11.4.2 Bargaining Power of Suppliers
  11.4.3 Bargaining Power of Buyers
  11.4.4 Threat of Substitutes
  11.4.5 Competitive Rivalry

12 INDUSTRY CHAIN ANALYSIS

12.1 AI Chip Thermal Packaging Industry Chain
12.2 AI Chip Thermal Packaging Upstream Analysis
12.3 AI Chip Thermal Packaging Midstream Analysis
12.4 AI Chip Thermal Packaging Downstream Analysis

13 RESEARCH FINDINGS AND CONCLUSION

14 APPENDIX

14.1 Methodology
14.2 Research Process and Data Source
14.3 Disclaimer

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

Table 1. Global AI Chip Thermal Packaging Consumption Value by Type, (USD Million), 2021 & 2025 & 2032
Table 2. Global AI Chip Thermal Packaging Consumption Value by Materials, (USD Million), 2021 & 2025 & 2032
Table 3. Global AI Chip Thermal Packaging Consumption Value by Application, (USD Million), 2021 & 2025 & 2032
Table 4. Global AI Chip Thermal Packaging Consumption Value by Region (2021-2026) & (USD Million)
Table 5. Global AI Chip Thermal Packaging Consumption Value by Region (2027-2032) & (USD Million)
Table 6. Samsung Electronics Company Information, Head Office, and Major Competitors
Table 7. Samsung Electronics Major Business
Table 8. Samsung Electronics AI Chip Thermal Packaging Product and Solutions
Table 9. Samsung Electronics AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 10. Samsung Electronics Recent Developments and Future Plans
Table 11. Rapidus? Company Information, Head Office, and Major Competitors
Table 12. Rapidus? Major Business
Table 13. Rapidus? AI Chip Thermal Packaging Product and Solutions
Table 14. Rapidus? AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 15. Rapidus? Recent Developments and Future Plans
Table 16. SK Hynix Company Information, Head Office, and Major Competitors
Table 17. SK Hynix Major Business
Table 18. SK Hynix AI Chip Thermal Packaging Product and Solutions
Table 19. SK Hynix AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 20. Amkor Technology Company Information, Head Office, and Major Competitors
Table 21. Amkor Technology Major Business
Table 22. Amkor Technology AI Chip Thermal Packaging Product and Solutions
Table 23. Amkor Technology AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 24. Amkor Technology Recent Developments and Future Plans

+357 96 030922
info@marketpublishers.com

Table 25. JCET Group Co., Ltd. Company Information, Head Office, and Major Competitors
Table 26. JCET Group Co., Ltd. Major Business
Table 27. JCET Group Co., Ltd. AI Chip Thermal Packaging Product and Solutions
Table 28. JCET Group Co., Ltd. AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 29. JCET Group Co., Ltd. Recent Developments and Future Plans
Table 30. Tongfu Microelectronics Co., Ltd. Company Information, Head Office, and Major Competitors
Table 31. Tongfu Microelectronics Co., Ltd. Major Business
Table 32. Tongfu Microelectronics Co., Ltd. AI Chip Thermal Packaging Product and Solutions
Table 33. Tongfu Microelectronics Co., Ltd. AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 34. Tongfu Microelectronics Co., Ltd. Recent Developments and Future Plans
Table 35. Huatian Technology Co., Ltd. Company Information, Head Office, and Major Competitors
Table 36. Huatian Technology Co., Ltd. Major Business
Table 37. Huatian Technology Co., Ltd. AI Chip Thermal Packaging Product and Solutions
Table 38. Huatian Technology Co., Ltd. AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 39. Huatian Technology Co., Ltd. Recent Developments and Future Plans
Table 40. Shanghai Xianfeng Technology Co., Ltd. Company Information, Head Office, and Major Competitors
Table 41. Shanghai Xianfeng Technology Co., Ltd. Major Business
Table 42. Shanghai Xianfeng Technology Co., Ltd. AI Chip Thermal Packaging Product and Solutions
Table 43. Shanghai Xianfeng Technology Co., Ltd. AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 44. Shanghai Xianfeng Technology Co., Ltd. Recent Developments and Future Plans
Table 45. Intel Company Information, Head Office, and Major Competitors
Table 46. Intel Major Business
Table 47. Intel AI Chip Thermal Packaging Product and Solutions
Table 48. Intel AI Chip Thermal Packaging Revenue (USD Million), Gross Margin and Market Share (2021-2026)
Table 49. Intel Recent Developments and Future Plans
Table 50. Global AI Chip Thermal Packaging Revenue (USD Million) by Players

+357 96 030922
info@marketpublishers.com

(2021-2026)
Table 51. Global AI Chip Thermal Packaging Revenue Share by Players (2021-2026)
Table 52. Breakdown of AI Chip Thermal Packaging by Company Type (Tier 1, Tier 2, and Tier 3)
Table 53. Market Position of Players in AI Chip Thermal Packaging, (Tier 1, Tier 2, and Tier 3), Based on Revenue in 2025
Table 54. Head Office of Key AI Chip Thermal Packaging Players
Table 55. AI Chip Thermal Packaging Market: Company Product Type Footprint
Table 56. AI Chip Thermal Packaging Market: Company Product Application Footprint
Table 57. AI Chip Thermal Packaging New Market Entrants and Barriers to Market Entry
Table 58. AI Chip Thermal Packaging Mergers, Acquisition, Agreements, and Collaborations
Table 59. Global AI Chip Thermal Packaging Consumption Value (USD Million) by Type (2021-2026)
Table 60. Global AI Chip Thermal Packaging Consumption Value Share by Type (2021-2026)
Table 61. Global AI Chip Thermal Packaging Consumption Value Forecast by Type (2027-2032)
Table 62. Global AI Chip Thermal Packaging Consumption Value by Application (2021-2026)
Table 63. Global AI Chip Thermal Packaging Consumption Value Forecast by Application (2027-2032)
Table 64. North America AI Chip Thermal Packaging Consumption Value by Type (2021-2026) & (USD Million)
Table 65. North America AI Chip Thermal Packaging Consumption Value by Type (2027-2032) & (USD Million)
Table 66. North America AI Chip Thermal Packaging Consumption Value by Application (2021-2026) & (USD Million)
Table 67. North America AI Chip Thermal Packaging Consumption Value by Application (2027-2032) & (USD Million)
Table 68. North America AI Chip Thermal Packaging Consumption Value by Country (2021-2026) & (USD Million)
Table 69. North America AI Chip Thermal Packaging Consumption Value by Country (2027-2032) & (USD Million)
Table 70. Europe AI Chip Thermal Packaging Consumption Value by Type (2021-2026) & (USD Million)
Table 71. Europe AI Chip Thermal Packaging Consumption Value by Type (2027-2032) & (USD Million)

+357 96 030922
info@marketpublishers.com

Table 72. Europe AI Chip Thermal Packaging Consumption Value by Application (2021-2026) & (USD Million)
Table 73. Europe AI Chip Thermal Packaging Consumption Value by Application (2027-2032) & (USD Million)
Table 74. Europe AI Chip Thermal Packaging Consumption Value by Country (2021-2026) & (USD Million)
Table 75. Europe AI Chip Thermal Packaging Consumption Value by Country (2027-2032) & (USD Million)
Table 76. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Type (2021-2026) & (USD Million)
Table 77. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Type (2027-2032) & (USD Million)
Table 78. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Application (2021-2026) & (USD Million)
Table 79. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Application (2027-2032) & (USD Million)
Table 80. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Region (2021-2026) & (USD Million)
Table 81. Asia-Pacific AI Chip Thermal Packaging Consumption Value by Region (2027-2032) & (USD Million)
Table 82. South America AI Chip Thermal Packaging Consumption Value by Type (2021-2026) & (USD Million)
Table 83. South America AI Chip Thermal Packaging Consumption Value by Type (2027-2032) & (USD Million)
Table 84. South America AI Chip Thermal Packaging Consumption Value by Application (2021-2026) & (USD Million)
Table 85. South America AI Chip Thermal Packaging Consumption Value by Application (2027-2032) & (USD Million)
Table 86. South America AI Chip Thermal Packaging Consumption Value by Country (2021-2026) & (USD Million)
Table 87. South America AI Chip Thermal Packaging Consumption Value by Country (2027-2032) & (USD Million)
Table 88. Middle East & Africa AI Chip Thermal Packaging Consumption Value by Type (2021-2026) & (USD Million)
Table 89. Middle East & Africa AI Chip Thermal Packaging Consumption Value by Type (2027-2032) & (USD Million)
Table 90. Middle East & Africa AI Chip Thermal Packaging Consumption Value by Application (2021-2026) & (USD Million)
Table 91. Middle East & Africa AI Chip Thermal Packaging Consumption Value by

+357 96 030922
info@marketpublishers.com

Application (2027-2032) & (USD Million)
Table 92. Middle East & Africa AI Chip Thermal Packaging Consumption Value by Country (2021-2026) & (USD Million)
Table 93. Middle East & Africa AI Chip Thermal Packaging Consumption Value by Country (2027-2032) & (USD Million)
Table 94. Global Key Players of AI Chip Thermal Packaging Upstream (Raw Materials)
Table 95. Global AI Chip Thermal Packaging Typical Customers

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

Figure 1. AI Chip Thermal Packaging Picture
Figure 2. Global AI Chip Thermal Packaging Consumption Value by Type, (USD Million), 2021 & 2025 & 2032
Figure 3. Global AI Chip Thermal Packaging Consumption Value Market Share by Type in 2025
Figure 4. Traditional Passive Thermal Packaging
Figure 5. Advanced Packaging Thermal Management Technology
Figure 6. Liquid Cooling Compatible Chip Packaging
Figure 7. Others
Figure 8. Global AI Chip Thermal Packaging Consumption Value by Materials, (USD Million), 2021 & 2025 & 2032
Figure 9. Global AI Chip Thermal Packaging Consumption Value Market Share by Materials in 2025
Figure 10. Thermal Interface Materials (TIM)
Figure 11. High Thermal Conductivity Thermal Dissipation Materials
Figure 12. Packaging Substrate Materials
Figure 13. Global AI Chip Thermal Packaging Consumption Value by Application, (USD Million), 2021 & 2025 & 2032
Figure 14. AI Chip Thermal Packaging Consumption Value Market Share by Application in 2025
Figure 15. Data Center AI Servers Picture
Figure 16. Autonomous Driving AI Chips Picture
Figure 17. Consumer Electronics AI Chips Picture
Figure 18. Others Picture
Figure 19. Global AI Chip Thermal Packaging Consumption Value, (USD Million): 2021 & 2025 & 2032
Figure 20. Global AI Chip Thermal Packaging Consumption Value and Forecast (2021-2032) & (USD Million)
Figure 21. Global Market AI Chip Thermal Packaging Consumption Value (USD Million) Comparison by Region (2021 VS 2025 VS 2032)
Figure 22. Global AI Chip Thermal Packaging Consumption Value Market Share by Region (2021-2032)
Figure 23. Global AI Chip Thermal Packaging Consumption Value Market Share by Region in 2025
Figure 24. North America AI Chip Thermal Packaging Consumption Value (2021-2032)

+357 96 030922
info@marketpublishers.com

& (USD Million)
Figure 25. Europe AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 26. Asia-Pacific AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 27. South America AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 28. Middle East & Africa AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 29. Company Three Recent Developments and Future Plans
Figure 30. Global AI Chip Thermal Packaging Revenue Share by Players in 2025
Figure 31. AI Chip Thermal Packaging Market Share by Company Type (Tier 1, Tier 2, and Tier 3) in 2025
Figure 32. Market Share of AI Chip Thermal Packaging by Player Revenue in 2025
Figure 33. Top 3 AI Chip Thermal Packaging Players Market Share in 2025
Figure 34. Top 6 AI Chip Thermal Packaging Players Market Share in 2025
Figure 35. Global AI Chip Thermal Packaging Consumption Value Share by Type (2021-2026)
Figure 36. Global AI Chip Thermal Packaging Market Share Forecast by Type (2027-2032)
Figure 37. Global AI Chip Thermal Packaging Consumption Value Share by Application (2021-2026)
Figure 38. Global AI Chip Thermal Packaging Market Share Forecast by Application (2027-2032)
Figure 39. North America AI Chip Thermal Packaging Consumption Value Market Share by Type (2021-2032)
Figure 40. North America AI Chip Thermal Packaging Consumption Value Market Share by Application (2021-2032)
Figure 41. North America AI Chip Thermal Packaging Consumption Value Market Share by Country (2021-2032)
Figure 42. United States AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 43. Canada AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 44. Mexico AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 45. Europe AI Chip Thermal Packaging Consumption Value Market Share by Type (2021-2032)
Figure 46. Europe AI Chip Thermal Packaging Consumption Value Market Share by

+357 96 030922
info@marketpublishers.com

Application (2021-2032)
Figure 47. Europe AI Chip Thermal Packaging Consumption Value Market Share by Country (2021-2032)
Figure 48. Germany AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 49. France AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 50. United Kingdom AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 51. Russia AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 52. Italy AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 53. Asia-Pacific AI Chip Thermal Packaging Consumption Value Market Share by Type (2021-2032)
Figure 54. Asia-Pacific AI Chip Thermal Packaging Consumption Value Market Share by Application (2021-2032)
Figure 55. Asia-Pacific AI Chip Thermal Packaging Consumption Value Market Share by Region (2021-2032)
Figure 56. China AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 57. Japan AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 58. South Korea AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 59. India AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 60. Southeast Asia AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 61. Australia AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 62. South America AI Chip Thermal Packaging Consumption Value Market Share by Type (2021-2032)
Figure 63. South America AI Chip Thermal Packaging Consumption Value Market Share by Application (2021-2032)
Figure 64. South America AI Chip Thermal Packaging Consumption Value Market Share by Country (2021-2032)
Figure 65. Brazil AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)

+357 96 030922
info@marketpublishers.com

Figure 66. Argentina AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 67. Middle East & Africa AI Chip Thermal Packaging Consumption Value Market Share by Type (2021-2032)
Figure 68. Middle East & Africa AI Chip Thermal Packaging Consumption Value Market Share by Application (2021-2032)
Figure 69. Middle East & Africa AI Chip Thermal Packaging Consumption Value Market Share by Country (2021-2032)
Figure 70. Turkey AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 71. Saudi Arabia AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 72. UAE AI Chip Thermal Packaging Consumption Value (2021-2032) & (USD Million)
Figure 73. AI Chip Thermal Packaging Market Drivers
Figure 74. AI Chip Thermal Packaging Market Restraints
Figure 75. AI Chip Thermal Packaging Market Trends
Figure 76. Porters Five Forces Analysis
Figure 77. AI Chip Thermal Packaging Industrial Chain
Figure 78. Methodology
Figure 79. Research Process and Data Source

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global AI Chip Thermal Packaging Market 2026 by Company, Regions, Type and Application, Forecast to 2032

Product link: https://marketpublishers.com/r/GE59578D35CFEN.html

Price: US$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/GE59578D35CFEN.html